Typical Analog Product

Example: TLE2022AMJGBEP

Prefix—TLE

군용사양 (미국)
SNJ = TI Interface, MIL-PRF-38535 (QML)
SN = Commercial Processing
TL = TI Linear Control Circuit
TLC = TI LinCMOS™
TLE = TI Excalibur
TLV = TI Linear Low Voltage
TPIC = TI Intelligent Power
AD = Analog Devices™ *
AM = Advanced Micro Devices™ *
LM = National Semiconductor™ *
LT = Linear Technology™ *
OP = PMI™ *
SE = Signetics™ *
μA = Fairchild™ *
THS = TI High Power
TPS = TI Power Supply

Unique Device Designator—2022A

A or B in last position = Upgrade

Temperature Range—M

M = -55°C to 125°C (applicable to all TI prefixes except SNJ)
Q = -40°C to 125°C
I = -40°C to 85°C
T = -40°C to 105°C

Package Type / Pin Count—JG

DA = Plastic Small Outline Package / 28, 30, 32 or 38
FK = Ceramic Leadless Chip Carrier / 20 or 28
GA = Ceramic Pin Grid Array / 84
HFG = Ceramic Flatpack / 84 or 164
J = Ceramic DIP / 8, 14, 16, 20 or 28
JG = Ceramic DIP / 8
U = Ceramic Flatpack /10
W = Ceramic Flatpack / 14 or 16
WD = Ceramic Flatpack / 56
L = Ceramic Leadless Chip Carrier / 20 or 28
PHP = Plastic Quad Flatpack PowerPad / 48
PCE = Plastic Quad Flatpack / 144 or 160
PWP = Plastic Power TSSOP / 14, 16, 20, 24 or 28
DW = Plastic Widebody (30 mil) SOIC / 16, 20, 24 or 28
TCP = Tape Carrier Package / Custom
PFB = Plastic Quad Flatpack / 48

Process Level—B

Blank = Standard Suffix, Commercial Processing
B = MIL-PRF-38535 (QML)

Enhanced Plastic—EP

* = Second Source